

ABSTRACT OF THE DISCLOSURE

Methods of manufacturing optical transceiver modules using lead frame connectors that connect optical sub-assemblies to printed circuit boards. The lead frame connectors include a conductive lead structure that is encased in an insert injection molded plastic casing. The lead frame connector is aligned with the leads that protrude from the back end of the corresponding optical sub-assembly (OSA). The leads pass through corresponding holes in the lead frame connector and are soldered to the conductors of the lead frame assembly. Once the soldering has been performed, the combined OSA and lead frame connector becomes a surface mount device that can then be mounted to the PCB. Assembling an optical transceiver using the lead frame connectors is generally less expensive and more reliable compared to the use of conventional flexible printed circuit board connectors.

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